RELIABILITY REPORT

FOR

MAX3232ESE+

PLASTIC ENCAPSULATED DEVICES

May 17, 2013

MAXIM INTEGRATED

160 RIO ROBLES

SAN JOSE, CA 95134

Approved by
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Quality Assurance
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Conclusion

The MAX3232ESE+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX3222/MAX3232/MAX3237/MAX3241 transceivers have a proprietary low-dropout transmitter output stage enabling true RS-232 performance from a 3.0V to 5.5V supply with a dual charge pump. The devices require only four small 0.1µF external charge-pump capacitors. The MAX3222, MAX3232, and MAX3241 are guaranteed to run at data rates of 120kbps while maintaining RS-232 output levels. The MAX3237 is guaranteed to run at data rates of 250kbps in the normal operating mode and 1Mbps in the MegaBaud(tm) operating mode, while maintaining RS-232 output levels. The MAX3222/MAX3232 have 2 receivers and 2 drivers. The MAX3222 features a 1µA shutdown mode that reduces power consumption and extends battery life in portable systems. Its receivers remain active in shutdown mode, allowing external devices such as modems to be monitored using only 1µA supply current. The MAX3222 and MAX3232 are pin, package, and functionally compatible with the industry-standard MAX242 and MAX232, respectively. The MAX3241 is a complete serial port (3 drivers/5 receivers) designed for notebook and subnotebook computers. The MAX3237 (5 drivers/3 receivers) is ideal for fast modem applications. Both these devices feature a shutdown mode in which all receivers can remain active while using only 1µA supply current. Receivers R1 (MAX3237/MAX3241) and R2 (MAX3241) have extra outputs in addition to their standard outputs. These extra outputs are always active, allowing external devices such as a modem to be monitored without forward biasing the protection diodes in circuitry that may have VCC completely removed. The MAX3222, MAX3232, and MAX3241 are available in space-saving TSSOP and SSOP packages.

II. Manufacturing Information

A. Description/Function:	3.0V to 5.5V, Low-Power, up to 1Mbps, True RS-232 Transceivers Using Four 0.1µF External Capacitors
B. Process:	S3
C. Number of Device Transistors:	2306
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, or Thailand
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	16-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-4773
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	115°C/W
K. Single Layer Theta Jc:	32°C/W
L. Multi Layer Theta Ja:	82.2°C/W
M. Multi Layer Theta Jc:	32°C/W

IV. Die Information

A. Dimensions:	61.811 X 109.8425 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{1000 \times 4340 \times 389 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 0.5 \times 10^{-9}$

$\lambda = 0.5$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.03 @ 25C and 0.5 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (ESD lot NDMCIA1E1A D/C 0643, Latch-Up lot NO3CJA595B D/C 0446)

The RU60-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-3000 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX3232ESE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C	DC Parameters	80	0	JAES7A6A4C, D/C 1226
	Biased	& functionality	80	0	JO3AM2550B, D/C 1023
	Time = 1000 hrs.		80	0	JO3AL2003A, D/C 0701
			149	0	NO3BJA2A9B, D/C 0609

Note 1: Life Test Data may represent plastic DIP qualification lots.